DATE: 08/13/2004



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cosmo

SMD LED :

KL-670UYG

 NO. 61L40005
 REV.

 SHEET 2 OF 9
 1

ELECTRONICS CORPORATION

Absolute maximum ratings (TA=25℃)		QG Green (AlGaInP)	Unit
Reverse voltage	VR	5	V
Forward current	IF	30	mA
Forward current(Peak)	Ifp	100	mA
1/10 Duty Cycle,0.1ms Pulse Width			
Power dissipation	Pd	50	mW
LED LAMPS:			
Operating temperature	Тор	-40~+85	°C
Storage temperature	Тят	-40~+85	°C
LED DISPLAYS:			
Operating temperature	Та	-40~+85	°C
Storage temperature	Тятс	-40~+85	°C

Operating characteristics (TA=25°C)		QG Green (AlGaInP)	Unit
Forward voltage(typ.) IF=20mA	VF	2.2	V
Forward voltage(max.) IF=20mA	VF	2.6	V
Reverse current(max.) V _R =5V	Ir	10	uA
Wavelength at dominant	λ d	575	nm
IF=20mA Wavelength at peak	λp	574	nm
emission(typ.) IF=20mA			
Spectral line half-width	Δ λ	25	nm
IF=20MA Capacitance VF=0V,f=1MHz	С	20	pF

ED :



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View Angle 2 ∂1/2=120°









DATE: 08/13/2004 **SMD LED :** NO. 61L40005 cosmo REV. **KL-670UYG** 1 **SHEET 8 OF 9 ELECTRONICS CORPORATION SOLDERING SMT REFLOW SOLDERING INSTRUCTIONS** 10 sec MAX Temp (°C) **TEMPERATURE** 230 4° C/sec max/ 140~160°C 4° C/sec max Time 35sec MAX -60~120sec-SOLDERING INSRTUCTIONS **DIP AND WAVE SOLDERING** IRON SOLDERING(WITH 1.5mm IRON TIP) **TYPES TEMPERATURE OF** MAXLMUM DISTANCE FORM **TEMPERATURE OF** MAXLMUM DISTANCE FROM THE SOLDERING SOLDERING SOLDER JOINT SOLDERING SOLDERING SOLDER JOINT BATH TIME **TO CASE** IRON TIME **TO CASE** >2mm **≦260°**C **≦260°**℃ **3S** 3S >2mm LEDS **≦260°**℃ **5S** >4mm **≦260°**℃ **5**S >4mm DISPLAYS ≤**260°**C 3S >2mm ≤**260°**C 3S >2mm ≦**260**°C 3S >2mm ≦**260**°C 3S >2mm DISPLAYS

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KL-670UYG

SMD HANDLING AND APPLICATION PRECAUTIONS

STORAGE

(1.1)It is recommended to store the devices in accordance with the following conditions:

Humidity: 60%RH Max.

Temperature: $5^{\circ}C \sim 30^{\circ}C$ (41°F ~ 86°F)

(1.2)Shelf life in sealed bag: 12 month at $<5^{\circ}C \sim 30^{\circ}C$ and <30%RH. After the package is opened, the products should be used within 72hrs. Or they should be kept at $\leq 20\%$ RH in zip -locked sealed bags.

DRY PACK AND BAKING

SMD LEDs are MOISTURE SENSITIVE devices. Avoid absorbing moisture at any time during transportation and/or storage. It is recommended to bake before soldering when the pack is unsealed after 72 hrs, or any suspicious moisture being found. Bake devices in accordance with the following conditions:

- (a) $60\pm3^{\circ}$ C x (12~24hrs) and <5%RH, taped reel type
- (b) $100\pm3^{\circ}C$ x (45min~1hr), loose packing type, or
- (c) $130\pm3^{\circ}C$ x (15~30min), loose packing type

ELECTRIC STATIC DISCHARGE(ESD) PROTECTION

Materials with GaN, InGaN, AlInGaP are STATIC SENSITIVE devices. They will be packed in anti-static bags. ESD protection must be deliberatively observed from the initial design stage. The static -electric discharge may result in severe malfunction of the devices. In the events of manual working in process, make sure the devices are well protected from ESD at any time. Surge before and during handling products.

NO. 61L40005 RI SHEET 9 OF 9

REV. 1